imall

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Complementary Dual General Purpose Amplifier Transistor

PNP and NPN Surface Mount

Features

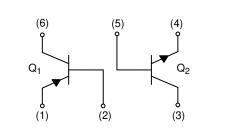
- High Voltage and High Current: $V_{CEO} = 50 \text{ V}$, $I_C = 200 \text{ mA}$
- High h_{FE} : $h_{FE} = 200 \sim 400$
- Moisture Sensitivity Level: 1
- ESD Rating
 - Human Body Model: 3A
 - Machine Model: C
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant*



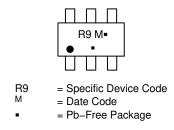
ON Semiconductor®

www.onsemi.com





MARKING DIAGRAM



ORDERING INFORMATION

	Device	Package	Shipping [†]
ŀ	HN1B01FDW1T1G	SC–74 (Pb–Free)	3,000/Tape & Reel
S	SHN1B01FDW1T1G	SC–74 (Pb–Free)	3,000/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit	
Collector-Base Voltage	V _{(BR)CBO}	60	Vdc	
Collector-Emitter Voltage	V _{(BR)CEO}	50	Vdc	
Emitter-Base Voltage	V _{(BR)EBO}	7.0	Vdc	
Collector Current – Continuous	۱ _C	200	mAdc	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Power Dissipation	PD	380	mW
Junction Temperature	TJ	150	°C
Storage Temperature	T _{stg}	-55 to +150	°C

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Q1: PNP

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Collector-Emitter Breakdown Voltage $(I_C = 2.0 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	-50	_	Vdc
Collector–Base Breakdown Voltage $(I_C = 10 \ \mu Adc, I_E = 0)$	V _{(BR)CBO}	-60	-	Vdc
Emitter–Base Breakdown Voltage $(I_E = 10 \ \mu Adc, I_C = 0)$	V _{(BR)EBO}	-7.0	_	Vdc
Collector–Base Cutoff Current $(V_{CB} = 45 \text{ Vdc}, I_E = 0)$	І _{СВО}	_	-0.1	μAdc
$ Collector-Emitter Cutoff Current \\ (V_{CE} = 10 \ Vdc, \ I_B = 0) \\ (V_{CE} = 30 \ Vdc, \ I_B = 0) \\ (V_{CE} = 30 \ Vdc, \ I_B = 0, \ T_A = 80^\circ C) $	I _{CEO}	- - -	-0.1 -2.0 -1.0	μAdc μAdc mAdc
DC Current Gain (Note 1) (V_{CE} = 6.0 Vdc, I _C = 2.0 mAdc)	h _{FE}	-200	-400	-
Collector–Emitter Saturation Voltage $(I_C = 100 \text{ mAdc}, I_B = 10 \text{ mAdc})$	V _{CE(sat)}	-	-0.3	Vdc

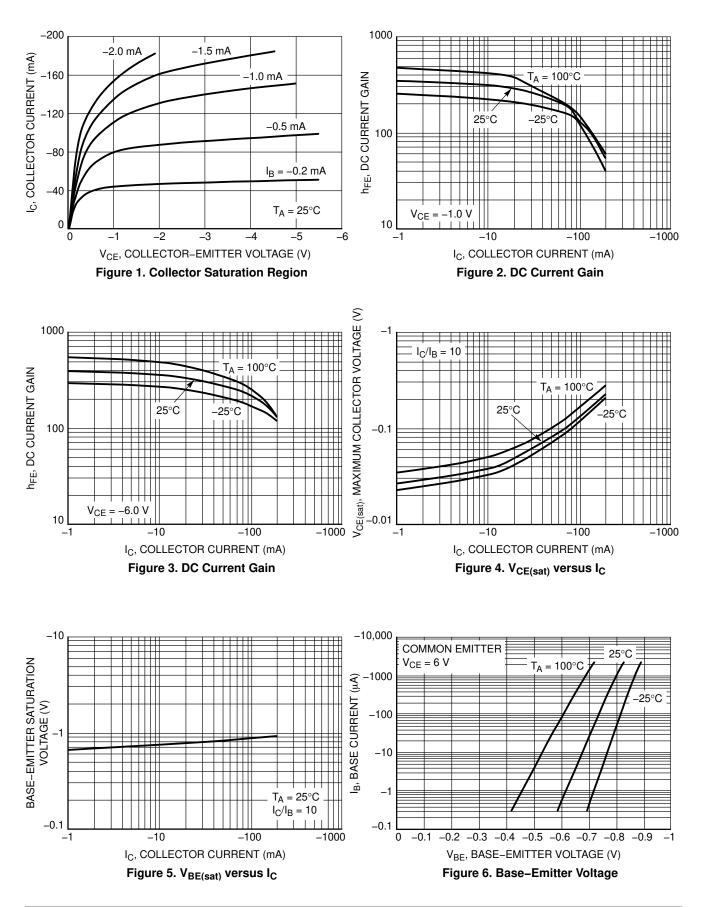
Q2: NPN

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

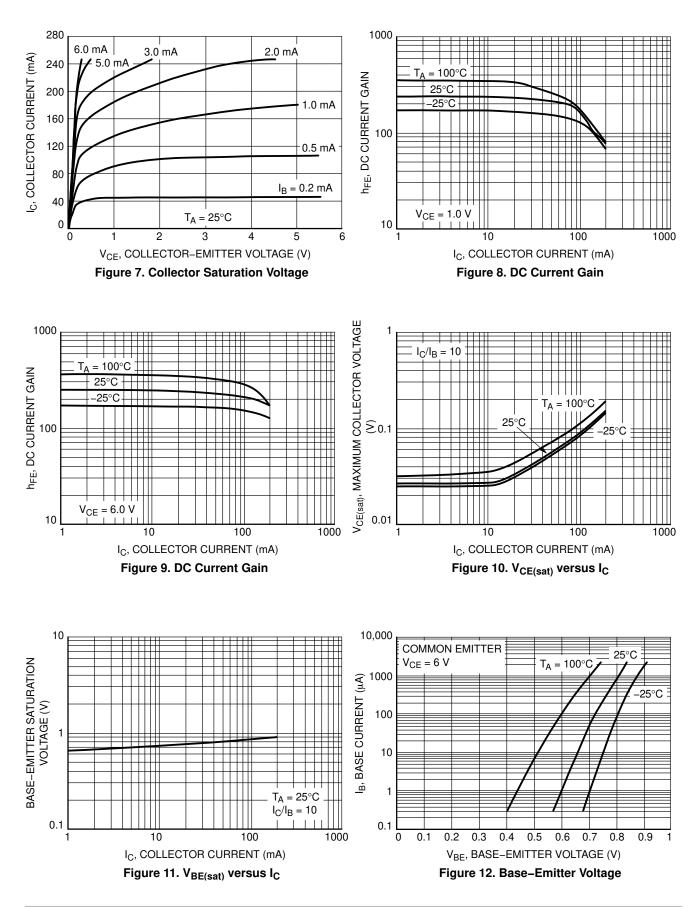
Characteristic	Symbol	Min	Max	Unit
Collector–Emitter Breakdown Voltage $(I_{C} = 2.0 \text{ mAdc}, I_{B} = 0)$	V _{(BR)CEO}	50	_	Vdc
Collector–Base Breakdown Voltage $(I_C = 10 \ \mu Adc, I_E = 0)$	V _{(BR)CBO}	60	-	Vdc
Emitter–Base Breakdown Voltage $(I_E = 10 \ \mu Adc, I_C = 0)$	V _{(BR)EBO}	7.0	-	Vdc
Collector-Base Cutoff Current ($V_{CB} = 45 \text{ Vdc}, I_E = 0$)	I _{CBO}	_	0.1	μAdc
	ICEO		0.1 2.0 1.0	μAdc μAdc mAdc
DC Current Gain (Note 1) (V _{CE} = 6.0 Vdc, I _C = 2.0 mAdc)	h _{FE}	200	400	-
Collector-Emitter Saturation Voltage (I _C = 100 mAdc, I _B = 10 mAdc)	V _{CE(sat)}	-	0.25	Vdc

1. Pulse Test: Pulse Width \leq 300 µs, D.C. \leq 2%.

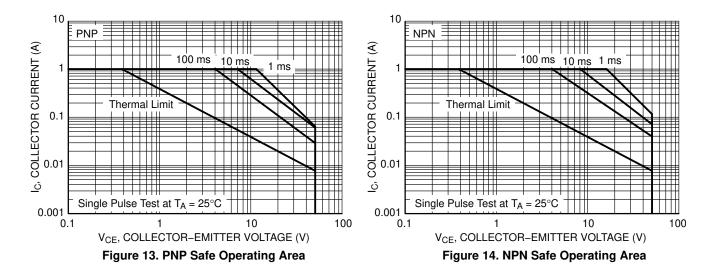
TYPICAL ELECTRICAL CHARACTERISTICS: PNP Transistor



TYPICAL ELECTRICAL CHARACTERISTICS: NPN Transistor

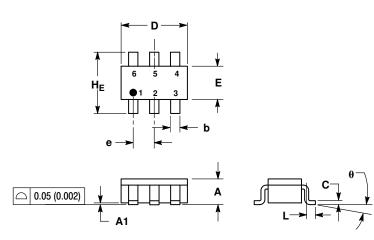


TYPICAL ELECTRICAL CHARACTERISTICS

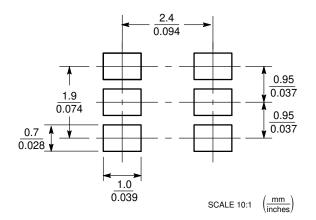


PACKAGE DIMENSIONS

SC-74 CASE 318F-05 **ISSUE N**



SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NOTES

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982
- CONTROLLING DIMENSION: INCH
- 3.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL. 318F-01, -02, -03, -04 OBSOLETE. NEW STANDARD 318F-05. 4.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.90	1.00	1.10	0.035	0.039	0.043
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.25	0.37	0.50	0.010	0.015	0.020
c	0.10	0.18	0.26	0.004	0.007	0.010
D	2.90	3.00	3.10	0.114	0.118	0.122
Е	1.30	1.50	1.70	0.051	0.059	0.067
е	0.85	0.95	1.05	0.034	0.037	0.041
L	0.20	0.40	0.60	0.008	0.016	0.024
ΗE	2.50	2.75	3.00	0.099	0.108	0.118
θ	0°	-	10°	0°	-	10°

STYLE 3: PIN 1. EMITTER 1 2. BASE 1 3. COLLECTOR 2 4. EMITTER 2 5. BASE 2 6. COLLECTOR 1

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